

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0	1.58	0.06
	Doped silicon	Silicon (Si)	7440-21-3	0.19	98.42	3.74
<b>Subtotal</b>				<b>0.19</b>	<b>100</b>	<b>3.8</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01	10.0	0.25
	Silver alloy	Silver (Ag)	7440-22-4	0	2.0	0.05
	Lead alloy	Lead (Pb)	7439-92-1	0.11	88.0	2.23
<b>Subtotal</b>				<b>0.12</b>	<b>100</b>	<b>2.53</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.07	100.0	1.31
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.4
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.06	0.8
	Copper alloy	Copper (Cu)	7440-50-8	67.3	99.91	1338.79
<b>Subtotal</b>				<b>67.36</b>	<b>100</b>	<b>1339.99</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.04	100.0	20.68
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.4	4.5	27.95
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.12	10.0	62.1
	Filler	Silica fused	60676-86-0	23.41	75.0	465.75
	Metal hydroxide	Metal hydroxide		3.12	10.0	62.1
	Carbon Black	Carbon black	1333-86-4	0.16	0.5	3.1
<b>Subtotal</b>				<b>31.21</b>	<b>100</b>	<b>621</b>
<b>Total</b>				<b>99.99</b>	<b>100</b>	<b>1989.31</b>

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